Internally Matched Power GaAs FETs (X, Ku-Band)

Features

- High power
  - P_{1dB} = 39.5 dBm at 8.5 GHz to 9.6 GHz
- High gain
  - G_{1dB} = 6.0 dB at 8.5 GHz to 9.6 GHz
- Broadband internally matched
- Hermetically sealed package

RF Performance Specifications (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Typ.	Max.
Output Power at 1dB Compression Point	P_{1dB}	V_{DS} = 9V f = 8.5 - 9.6 GHz	dBm	38.5	39.5	–
Power Gain at 1dB Compression Point	G_{1dB}		dB	5.0	6.0	–
Drain Current	I_{DS}		A	–	3.4	4.4
Power Added Efficiency	η_{add}		%	–	22	–
Channel-Temperature Rise	ΔT_{ch}	V_{DS} x I_{DS} x $R_{th\ (c-c)}$	°C	–	–	80

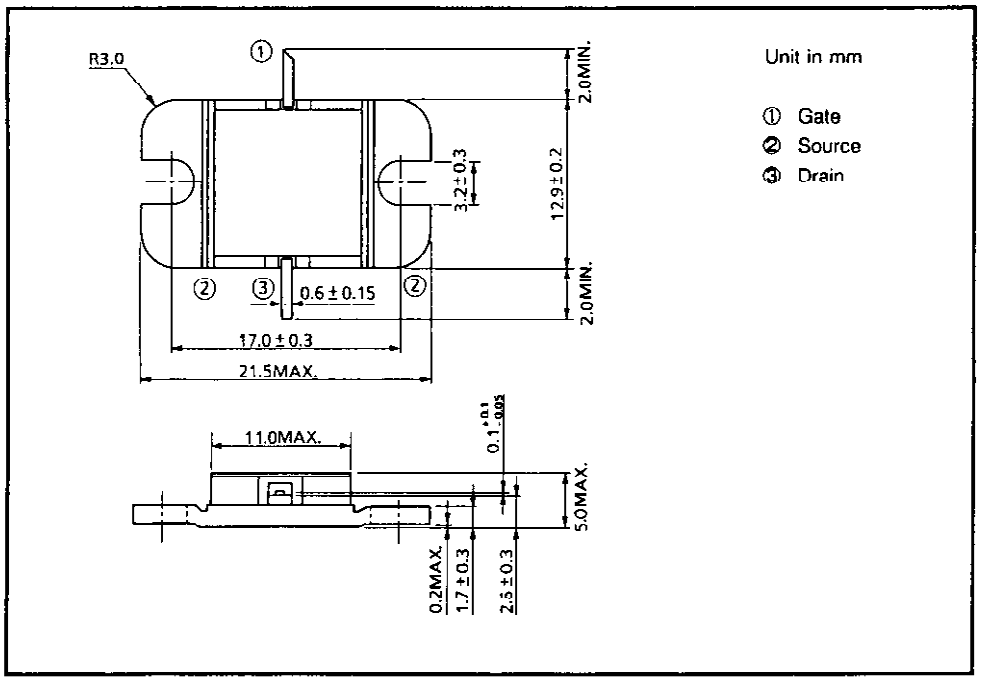
Electrical Characteristics (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Typ.	Max.
Transconductance	gm	V_{DS} = 3V I_{DS} = 4.0A	mS	–	2400	–
Pinch-off Voltage	V_{GSoff}	V_{DS} = 3V I_{DS} = 120 mA	V	-2	-3.5	–5
Saturated Drain Current	I_{DSS}	V_{DS} = 3V V_{GS} = 0V	A	–	8.0	10.4
Gate-Source Breakdown Voltage	V_{GSO}	I_{GS} = -120 μA	V	-5	–	–
Thermal Resistance	$R_{th\ (c-c)}$	Channel to Case	°C/W	–	1.6	2.5

Absolute Maximum Ratings (T_a = 25°C)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V_{DS}	V	15
Gate-Source Voltage	V_{GS}	V	-5
Drain Current	I_D	A	10.4
Total Power Dissipation (T_c = 25°C)	P_T	W	60
Channel Temperature	T_{ch}	°C	175
Storage Temperature	T_{stg}	°C	-65 ~ 175

Package Outline (2-11C1B)

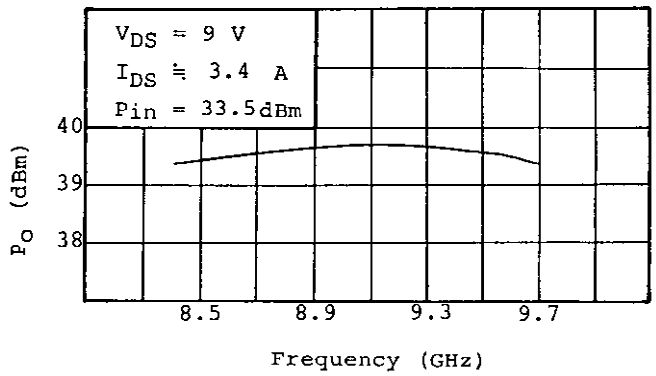


Handling Precautions for Packaged Type

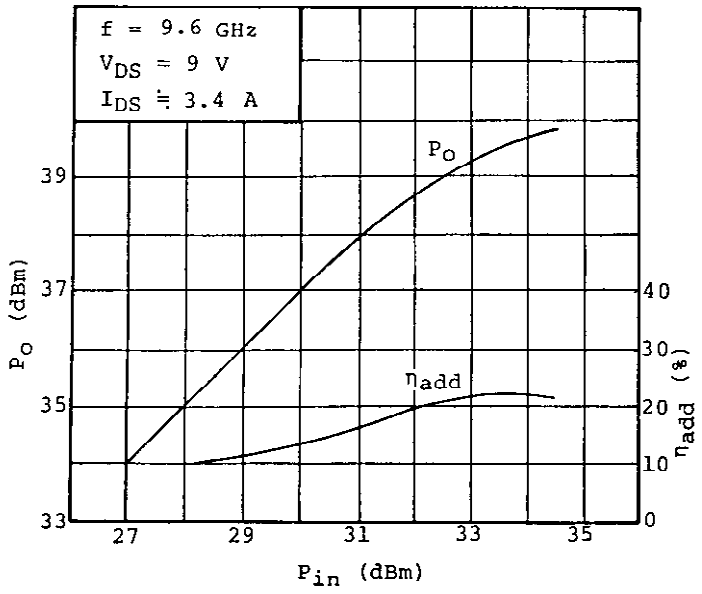
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF Performances

Output Power vs. Frequency



Output Power vs. Input Power



Power Dissipation vs. Case Temperature